

L Number	Hits	Search Text	DB	Time stamp
101	10	"6119367" and (heat or heated or heater)	USPAT	2004/09/30 11:54
-	57	"5569330"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 07:42
-	4	((("5569330") or ("5571337"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 07:45
-	3	((WAFER or semiconductor or substrate) near20 (raised or raising or lifted or withdrawn)) same ("air knife" or "air wipe") and (washing or wash or clean or cleaning or rinse or rinsing or dry or drying)	USOCR	2004/09/30 10:00
-	20	((WAFER or semiconductor or substrate) near20 (raised or raising or lifted or withdrawn)) same ("air knife" or "air wipe") and (washing or wash or clean or cleaning or rinse or rinsing or dry or drying)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 07:51
-	37	134/902.ccls. and ("air knife" or "air wipe")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 07:54
-	0	134/902.ccls. and ("air knife" or "air wipe")	USOCR	2004/09/30 07:55
-	2201	134/902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 08:04
-	1481	134/902.ccls. and (tank or container or vessel or receptacle or bath or vat or tub)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 10:00
-	4	134/34.ccls. and (wafer or semiconductor or substrate) same ("air knife" or "air wipe")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 10:50
-	2	("6199564").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 10:28
-	3	("3865298").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 10:29
-	2339	(wafer or semiconductor or substrate) same ("air knife" or "air wipe")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 10:51
-	1021	(wafer or semiconductor or substrate) same ("air knife" or "air wipe") same (drying or dry or dried)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/30 10:51
-	1023	(wafer or semiconductor or substrate) same ("air knife" or "air wipe") same (drying or dry or dried)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/30 10:52
-	138	(wafer or semiconductor or substrate) same ("air knife" or "air wipe") same (drying or dry or dried)	USOCR	2004/09/30 10:54
-	3	((wafer or semiconductor or substrate) NEAR25 (pulled or lifted or raised or withdrawn)) same ("air knife" or "air wipe") same (drying or dry or dried)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/30 10:56

-	36	((wafer or semiconductor or substrate)· NEAR25 (pulled or lifted or raised or withdrawn)) same ("air knife" or "air wipe")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 10:58
-	428	((wafer or semiconductor or substrate) NEAR25 (pulled or lifted or raised or withdrawn)) same (((air or gas) near15 (nozzle or jet)) or "air knife" or "air wipe")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 11:04
-	511	134/113.ccls.	USPAT	2004/09/30 11:52